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In the abstract:

Replace the abstract with the following version.

--A polishing pad with a layer that provides a polishing surface. The layer has a thickness between about 0.06 and 0.12 inches, and a plurality of substantially circular grooves having a depth between about 0.02 and 0.05 inches are formed in the polishing surface.--

REMARKS

Attached is a marked-up version of the changes being made by the current amendment.

Applicant asks that all claims be examined.

Please apply any other charges or credits to Deposit Account No. 06-1050.

Respectfully submitted,

Date: 10/29/61

David J. Goren 'Reg. No. 34,609

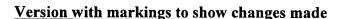
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50065988.doc

Applicant : Osterheld et a Serial No. : Unassigned Filed : October 29, 2001

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In the specification:

The paragraph beginning at page 1, line 6, has been amended as follows:

This application is a <u>continuation of pending U.S. Application Serial No. 09/441,633</u>, filed November 16, 1999, which is a divisional of U.S. Application Serial No. 09/003,315, filed <u>January 6,1998</u>, now issued as U.S. Patent No. 5,984,769, which is continuation-in-part of U.S. Application Serial No. 08/856,948, filed May 15, 1997, now issued as U.S. Patent No. 5,921,855, the entire disclosures of which [is] <u>are</u> incorporated herein by reference.

In the claims:

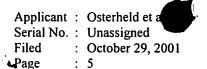
Claims 1-42 have been cancelled.

Claims 43-54 have been added as follows:

43. (New) A polishing pad for polishing a substrate in a chemical mechanical polishing system, comprising:

a layer having a thickness between about 0.06 and 0.12 inches, one side of the layer providing a polishing surface and having a plurality of substantially circular grooves formed therein, the grooves having a depth between about 0.02 and 0.05 inches.

- 44. (New) The polishing pad of claim 43, wherein the grooves have a depth of approximately 0.03 inches.
- 45. (New) The polishing pad of claim 43, wherein the grooves have a width between about 0.015 and 0.04 inches.
- 46. (New) The polishing pad of claim 45, wherein the grooves have a width of approximately 0.02 inches.



47. (New) The polishing pad of claim 43, wherein the grooves have a pitch between about 0.09 and 0.24 inches.

- 48. (New) The polishing pad of claim 47, wherein the grooves have a pitch of approximately 0.12 inches.
- 49. (New) The polishing pad of claim 43, wherein the grooves are concentrically arranged.
- 50. (New) The polishing pad of claim 43, wherein the grooves are uniformly spaced over the polishing surface.
- 51. (New) The polishing pad of claim 43, wherein the polishing pad further comprises a lower layer on a side of the layer opposite the polishing surface.
- 52. (New) The polishing pad of claim 51, wherein a distance between a bottom of the grooves and the lower layer is between about 0.035 and 0.085 inches.
- 53. (New) The polishing pad of claim 52, wherein the distance between a bottom of the grooves and the lower layer is about 0.04 inches.
- 54. (New) The polishing pad of claim 51, wherein the thickness of the layer of is about 0.07 inches.

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